

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L2	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L3	56306	(solder near bump\$1) or (solder near ball\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L4	6292	L1 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L5	543	L2 and L3 and L4	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L6	525	L5 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L7	54	L6 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49
L8	20	L7 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:49

L9	117	16 and plasma	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 18:52
L10	0	("2005/0155790").URPN.	USPAT	ADJ	ON	2008/11/03 19:42
L11	0	"2002256288"	USPAT	ADJ	ON	2008/11/03 19:42
L12	1	"2002-256288"	USPAT	ADJ	ON	2008/11/03 19:42
S1	5	"2004103928"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:14
S2	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 14:20
S3	4	"2002057186"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:24
S4	2	"2003179100"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S5	3	"2002343829"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:25
S6	2	"2000138255"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:26

S7	1	"10594844"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:38
S8	2	"20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:43
S9	1	"9172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S10	0	"009172035"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:53
S11	2	9-172035	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 17:54
S12	2	"5088189".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S13	2	"6028011".pn.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05
S14	107091	wiring near board	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:05

S15	1787	solder near resist near film	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S16	16	S14 near S15	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/10/28 18:06
S17	2	US "20040046252"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:03
S18	914276	(wiring or circuit or (printed near circuit) or support) near (board or substrate or base) or PCB	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:28
S19	45462	(flip near chip) or flip-chip	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:28
S20	56306	(solder near bump\$1) or (solder near ball\$1)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29
S21	6292	S18 same (solder near resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29
S22	13703	S18 and S19 and S20	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:29

S23	543	S19 and S20 and S21	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:30
S24	446	S23 and thickness	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 10:47
S25	4	"11077930"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 11:04
S26	0	("7005585").URPN.	USPAT	ADJ	ON	2008/11/03 11:05
S27	14	"4859808"	USPAT	ADJ	ON	2008/11/03 11:05
S28	1	"4859808".pn.	USPAT	ADJ	ON	2008/11/03 11:30
S29	1	"5218234".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S30	1	"5378859".pn.	USPAT	ADJ	ON	2008/11/03 11:31
S31	1	"5397864".pn.	USPAT	ADJ	ON	2008/11/03 11:32
S32	1	"5650595".pn.	USPAT	ADJ	ON	2008/11/03 11:33
S33	0	S23 and (thickness ner resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S34	49	S23 and (thickness near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:00
S35	3	S23 and (thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:06

S36	111	(thickness near underfill)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:07
S37	52	S23 and (thickness near solder resist)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 12:17
S38	3	"20050155790"	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:29
S39	525	S23 and method	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S40	125	S39 and pressing	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 13:58
S41	0	S39 and (deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S42	11	(deposit near liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36
S43	54	S39 and (liquid near resin)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	ADJ	ON	2008/11/03 14:36

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